

370HR

High Performance Laminate and Prepreg Materials

370HR is the industry's "best in class" lead-free compatible product for high-reliability applications across the telecommunications and high-end automotive markets.

370HR is a high performance 180°C glass transition temperature (Tg) FR-4 system for multilayer Printed Wiring Board (PWB) applications where maximum thermal performance and reliability are required.

370HR laminate and prepreg products are manufactured with a unique high performance multifunctional expoxy resin, reinforced with electrical grade (E-glass) glass fabric. This system provides improved thermal performance and low expansion rates in comparison to traditional FR-4 while retaining FR-4 processability.

In addition to this superior thermal performance, the mechanical, chemical and moisture resistance properties all equal or exceed the performance of traditional FR-4 materials. The 370HR system is also laser fluorescing and UV blocking for maximum compatibility with Automated Optical Inspection (AOI) systems, optical positioning systems with photoimagable solder mask imaging.

370HR has proven to be best in class for sequential lamination designs.

Product Attributes

High Thermal Reliability High Density Interconnect Computing, Storage & Peripherals
Consumer Electronics
Networking & Communication Systems
Aerospace & Defense
Medical, Industrial & Instrumentation
Automotive & Transportation

ORDERING INFORMATION:

Contact your local sales representative or visit www.isola-group.com for further information.

Isola Group 3100 West Ray Road Suite 301 Chandler, AZ 85226 Phone: 480-893-6527 Fax: 480-893-1409 info@isola-group.com Isola Asia Pacific (Hong Kong) Ltd. Unit 3512 - 3522, 35/F No. 1 Hung To Road, Kwun Tong, Kowloon, Hong Kong Phone: 852-2418-1318 Fax: 852-2418-1533 info.hkg@isola-group.com Isola GmbH Isola Strasse 2 D-52348 Düren, Germany Phone: 49-2421-8080 Fax: 49-2421-808164 info-dur@isola-group.com



Product Features

- · Industry Recognition
 - UL File Number: E41625
 - Qualified to UL's MCIL Program
 - RoHS Compliant
- · Performance Attributes
 - CAF resistant
- · Processing Advantages
 - FR-4 process compatible
 - UV blocking and AOI fluorescence

Product Availability

- · Standard Material Offering: Laminate
 - 2 to 125 mil (0.05 to 3.2 mm)
 - Available in full size sheet or panel form
- · Copper Foil Type
 - HTE Grade 3
 - RTF (Reverse Treat Foil)
- · Copper Weight
 - $\frac{1}{2}$ to 2 oz (18 to 70 μ m) available
 - Heavier copper available
 - Thinner copper foil available
- · Standard Material Offering: Prepreg
 - Roll or panel form
 - Tooling of prepreg panels
- · Glass Fabric Availability
 - E-glass
 - Square weave glass
 - Mechanically spread glass

Property		Typical Value	Units	Test Method
			Metric (English)	IPC-TM-650 (or as noted)
Glass Transition Temperature (Tg) by DSC		180	°C	2.4.25C
Decomposition Temperature (Td) by TGA @ 5% weight loss		340	°C	2.4.24.6
Time to Delaminate by TMA (Copper removed)	A. T260 B. T288	60 30	Minutes	2.4.24.1
Z-Axis CTE	A. Pre-Tg B. Post-Tg C. 50 to 260°C, (Total Expansion)	45 230 2.8	ppm/°C ppm/°C %	2.4.24C
X/Y-Axis CTE	Pre-Tg	13/14	ppm/°C	2.4.24C
Thermal Conductivity		_	W/mK	ASTM E1952
Thermal Stress 10 sec @ 288°C (550.4°F)	A. Unetched B. Etched	Pass	Pass Visual	2.4.13.1
Dk, Permittivity	A. @ 100 MHz B. @ 1 GHz C. @ 2 GHz D. @ 5 GHz E. @ 10 GHz	4.24 4.17 4.04 3.92 3.92	-	2.5.5.3 2.5.5.9 Bereskin Stripline Bereskin Stripline Bereskin Stripline
Df, Loss Tangent	A. @ 100 MHz B. @ 1 GHz C. @ 2 GHz D. @ 5 GHz E. @ 10 GHz	0.0150 0.0161 0.0210 0.0250 0.0250	- - -	2.5.5.3 2.5.5.9 Bereskin Stripline 2.5.5.5 2.5.5.5
Volume Resistivity	A. After moisture resistance B. At elevated temperature	3.0 x 10 ⁸ 7.0 x 10 ⁸	M⊠-cm	2.5.17.1
Surface Resistivity	A. After moisture resistance B. At elevated temperature	3.0×10^6 2.0×10^8	M⊠	2.5.17.1
Dielectric Breakdown		>50	kV	2.5.6B
Arc Resistance		115	Seconds	2.5.1B
Electric Strength (Laminate & laminated prepreg)		54 (1350)	kV/mm (V/mil)	2.5.6.2A
Comparative Tracking Index (CTI)		3 (175-249)	Class (Volts)	UL 746A ASTM D3638
Peel Strength	A. Low profile copper foil and very low profile copper foil all copper foil >17 @m [0.669 mil] B. Standard profile copper 1. After thermal stress 2. At 125°C (257°F) 3. After process solutions	1.14 (6.5) 1.25 (7.0) 1.25 (7.0) 1.14 (6.5)	N/mm (lb/inch)	2.4.8C 2.4.8.2A 2.4.8.3 2.4.8.3
Flexural Strength	A. Length direction B. Cross direction	90,000 77,000		2.4.4B
Tensile Strength	A. Length direction B. Cross direction	55,900 35,620		ASTM D3039
Poisson's Ratio	A. Length direction B. Cross direction	0.177 0.171	_	ASTM D3039
Moisture Absorption		0.15	%	2.6.2.1A
Flammability (Laminate & laminated prepreg)		V-0	Rating	UL 94
Max Operating Temperature		130	°C	UL 796

The data, while believed to be accurate and based on analytical methods considered to be reliable, is for information purposes only. Any sales of these products will be governed by the terms and conditions of the agreement under which they are sold.

